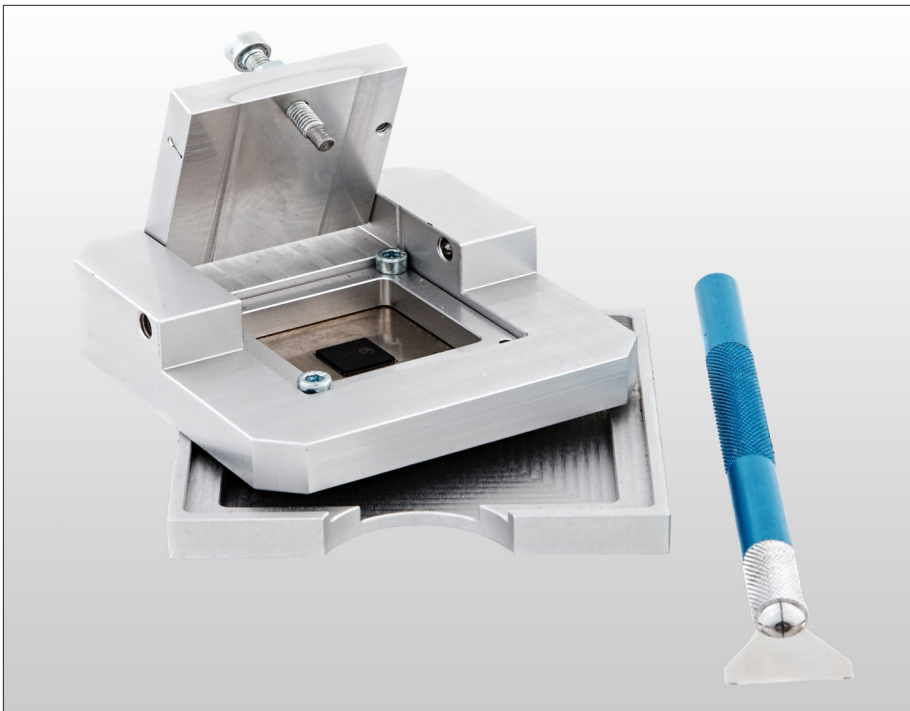


PASTE ON DEVICE QFN

ACCESSORIES 4.302

APPLICATIONS: SMT

ZEVAC LINE: ONYX



The option paste on device QFN is used for application of solder paste onto the components.

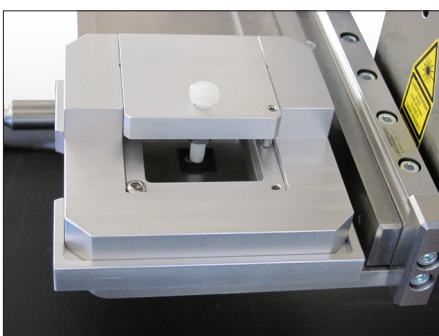
The tool is designed for using on the semi-automatic rework systems ONYX.

The interchangeable stencil allows the handling of the tool for a wide range of components.

The handling is very easy and does not require additional programming effort.

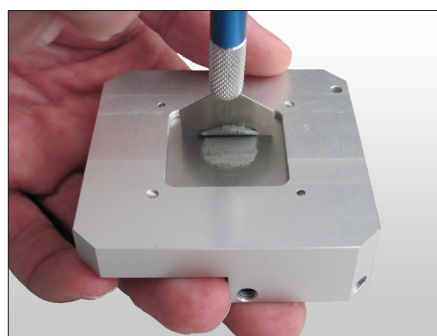
The solder paste is applied by the operator before the component is picket directly from the tool.

HANDLING



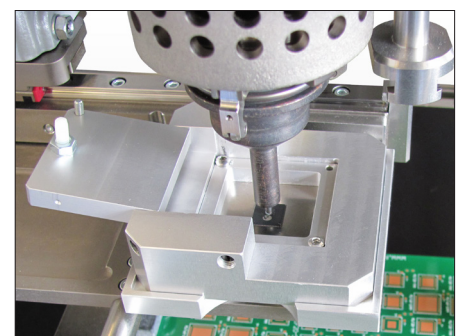
The component specific stencil is inserted in the multi-functional tool for pasting on device QFN.

The component is placed in the tool and held down by the fixation at the exact position.



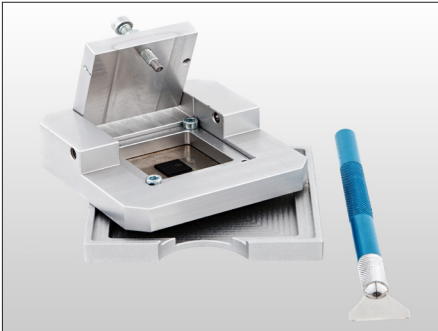
By using the squeegee on top of the stencil, an even amount of paste is applied onto the component.

After applying the paste, the complete tool is placed in the machine adaption and the fixation of the component can be removed.

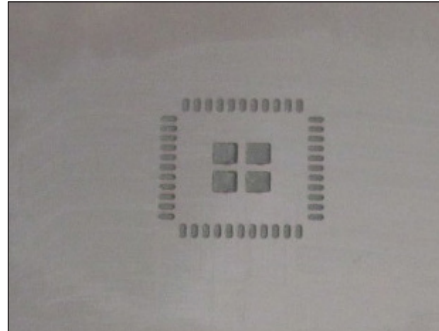


Afterwards the component is picked as usual by means of the force measurement, aligned with the vision unit and placed on the PCB.

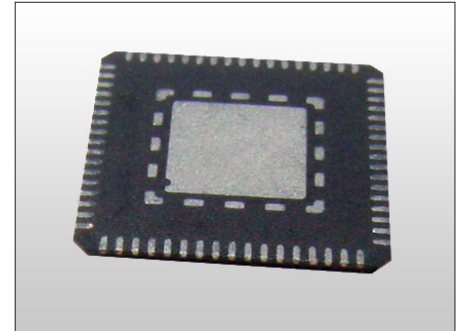
ORDER INFORMATION



The Paste on Device QFN option is delivered completely with stencils (3 layouts with 2 pieces each) and a squeegee. The layout of the stencil is defined according to the QFN component.



The stencil layout is defined by the component datasheet or according to customer specification.



Also Gerber-data can be used for producing the stencils.

Technical Data Subject to Change

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